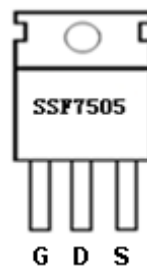


Main Product Characteristics:

V_{DSS}	75V
$R_{DS(on)}$	3.3mohm(typ.)
I_D	170A


TO220

Marking and pin Assignment

Schematic diagram
Features and Benefits:

- Advanced trench MOSFET process technology
- Special designed for PWM, load switching and general purpose applications
- Ultra low on-resistance with low gate charge
- Fast switching and reverse body recovery
- 175°C operating temperature


Description:

It utilizes the latest trench processing techniques to achieve the high cell density and reduces the on-resistance with high repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in power switching application and a wide variety of other applications

Absolute max Rating:

Symbol	Parameter	Max.	Units
$I_D @ TC = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ ①	170	A
$I_D @ TC = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ ①	110	
I_{DM}	Pulsed Drain Current②	670	
$P_D @ TC = 25^\circ C$	Power Dissipation③	272	W
	Linear Derating Factor	2.0	W/°C
V_{DS}	Drain-Source Voltage	75	V
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy @ $L=0.3mH$ ②	960	mJ
I_{AR}	Avalanche Current @ $L=0.3mH$ ②	80	A
$T_J T_{STG}$	Operating Junction and Storage Temperature Range	-55 to + 175	°C

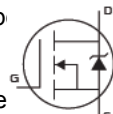
Thermal Resistance

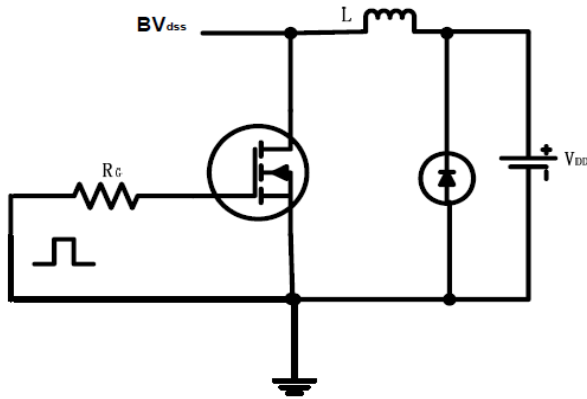
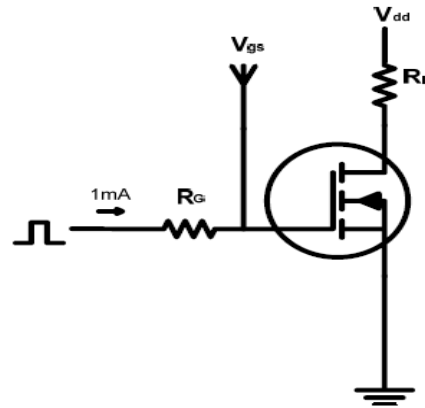
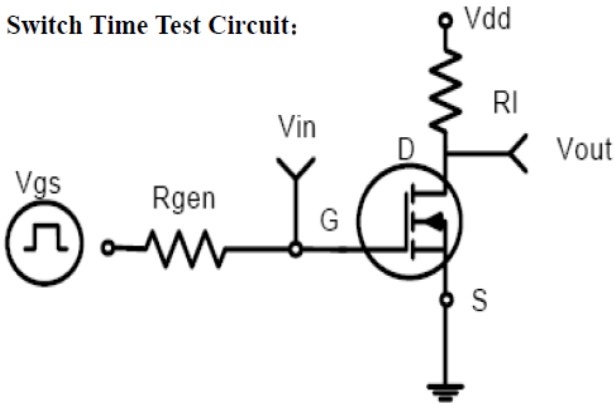
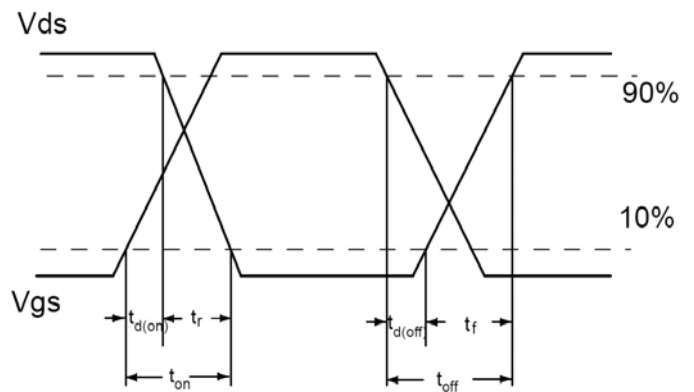
Symbol	Characterizes	Typ.	Max.	Units
R _{θJC}	Junction-to-case ^③	—	0.55	°C/W
R _{θJA}	Junction-to-ambient (t ≤ 10s) ^④	—	62	°C/W
	Junction-to-Ambient (PCB mounted, steady-state) ^④	—	40	°C/W

Electrical Characterizes @T_A=25°C unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source breakdown voltage	75	—	—	V	V _{GS} = 0V, I _D = 250μA
R _{DS(on)}	Static Drain-to-Source on-resistance	—	3.3	5	mΩ	V _{GS} =10V, I _D = 30A T _J = 125°C
		—	6.25	—		
V _{GS(th)}	Gate threshold voltage	2	—	4	V	V _{DS} = V _{GS} , I _D = 250μA T _J = 125°C
		—	2.0	—		
I _{DSS}	Drain-to-Source leakage current	—	—	1	μA	V _{DS} = 75V, V _{GS} = 0V T _J = 125°C
		—	—	50		
I _{GSS}	Gate-to-Source forward leakage	—	—	100	nA	V _{GS} = 20V
		-100	—	—		V _{GS} = -20V
Q _g	Total gate charge	—	221	—	nC	I _D = 30A, V _{DS} =30V, V _{GS} = 10V
Q _{gs}	Gate-to-Source charge	—	42	—		
Q _{gd}	Gate-to-Drain("Miller") charge	—	70	—		
t _{d(on)}	Turn-on delay time	—	25	—	ns	V _{GS} =10V, V _{DS} =30V, R _L =15Ω, R _{GEN} =2.55Ω
t _r	Rise time	—	24	—		
t _{d(off)}	Turn-Off delay time	—	125	—		
t _f	Fall time	—	53	—		
C _{iss}	Input capacitance	—	9139	—	pF	V _{GS} = 0V V _{DS} = 25V f = 600KHz
C _{oss}	Output capacitance	—	757	—		
C _{rss}	Reverse transfer capacitance	—	669	—		

Source-Drain Ratings and Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I _S	Continuous Source Current (Body Diode)	—	—	170	A	MOSFET symb showing the integral reverse p-n junction diode. 
I _{SM}	Pulsed Source Current (Body Diode)	—	—	670	A	
V _{SD}	Diode Forward Voltage	—	0.84	1.3	V	I _S =30A, V _{GS} =0V
t _{rr}	Reverse Recovery Time	—	47	—	ns	T _J = 25°C, I _F = 75A, di/dt =
Q _{rr}	Reverse Recovery Charge	—	97	—	nC	100A/μs

Test circuits and Waveforms
EAS test circuits:

Gate charge test circuit:

Switch Time Test Circuit:

Switch Waveforms:

Notes:

- ① The maximum current rating is limited by bond-wires.
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ The power dissipation PD is based on max. junction temperature, using junction-to-case thermal resistance.
- ④ The value of $R_{\theta JA}$ is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$
- ⑤ These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)} = 175^\circ C$.
- ⑥ The maximum current rating is limited by bond-wires.

Typical electrical and thermal characteristics

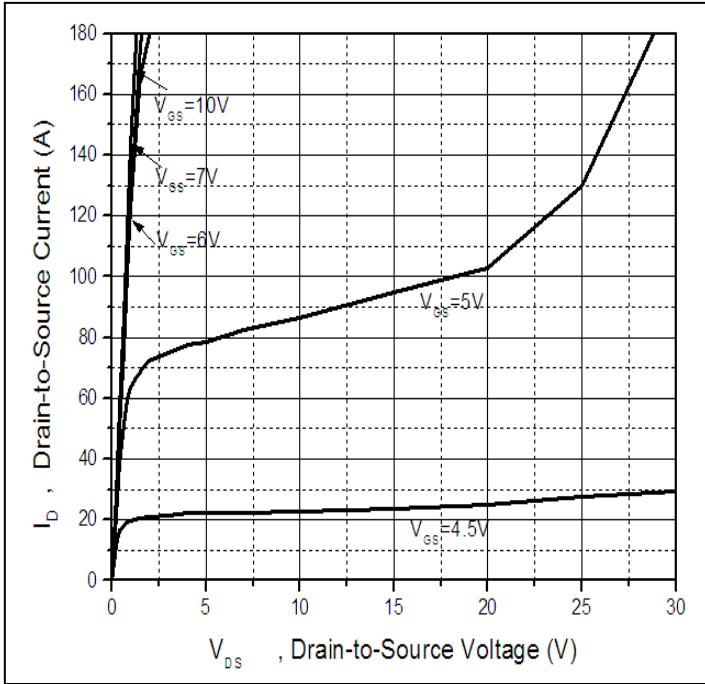


Figure 1: Typical Output Characteristics

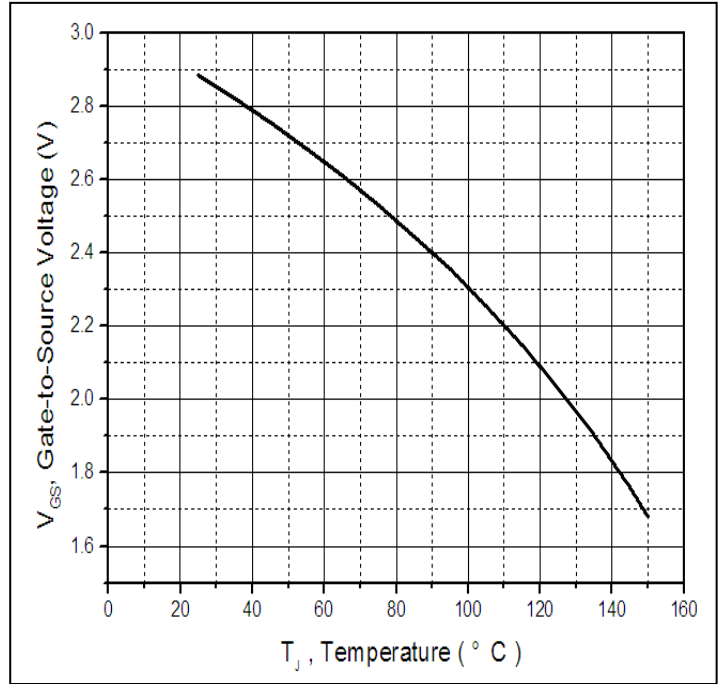


Figure 2. Gate to source cut-off voltage

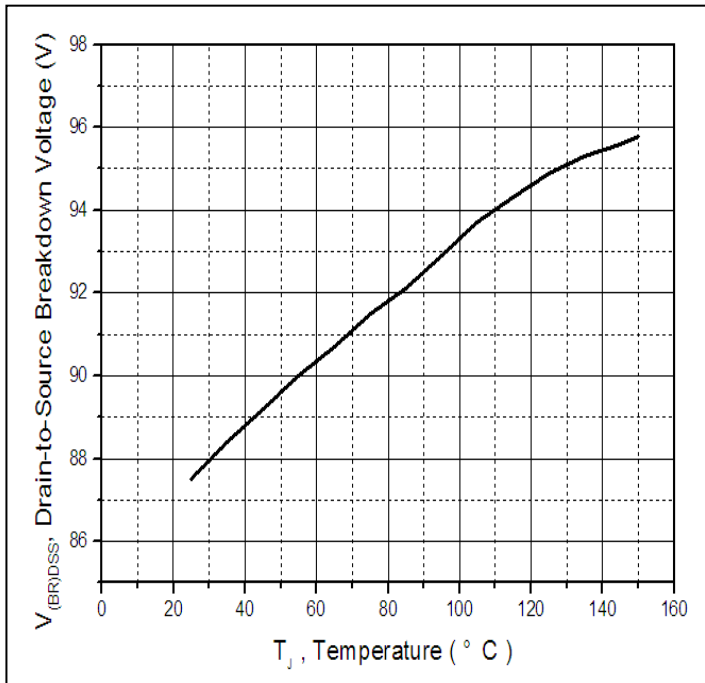


Figure 3. Drain-to-Source Breakdown Voltage vs. Temperature

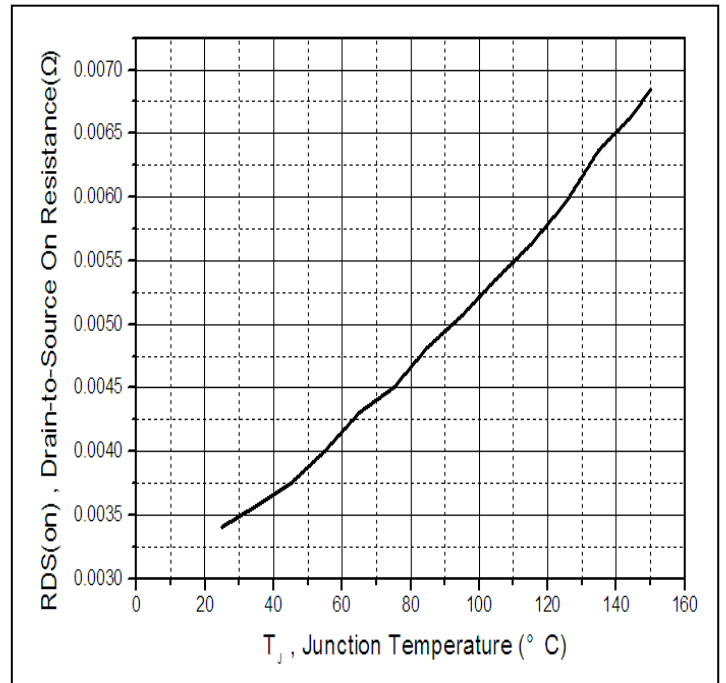


Figure 4: Normalized On-Resistance Vs. Case Temperature

Typical electrical and thermal characteristics

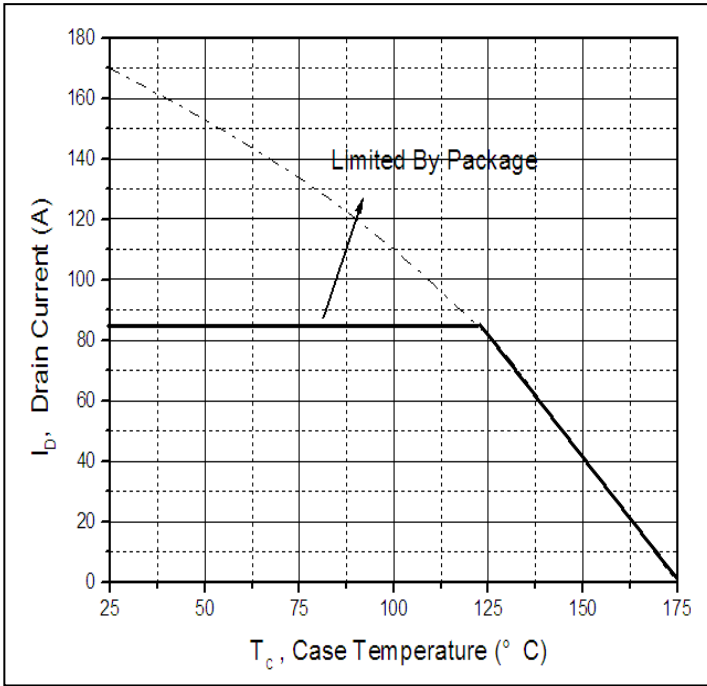


Figure 5. Maximum Drain Current Vs. Case Temperature

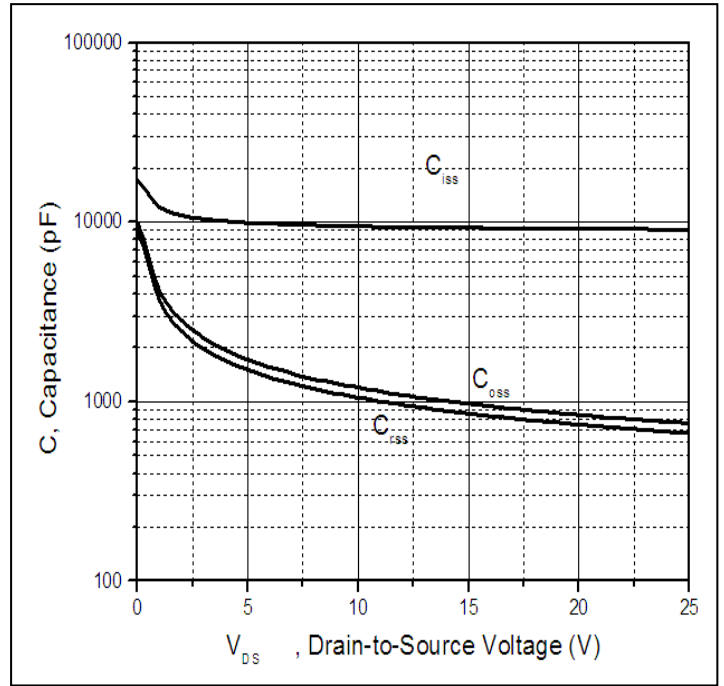


Figure 6. Typical Capacitance Vs. Drain-to-Source Voltage

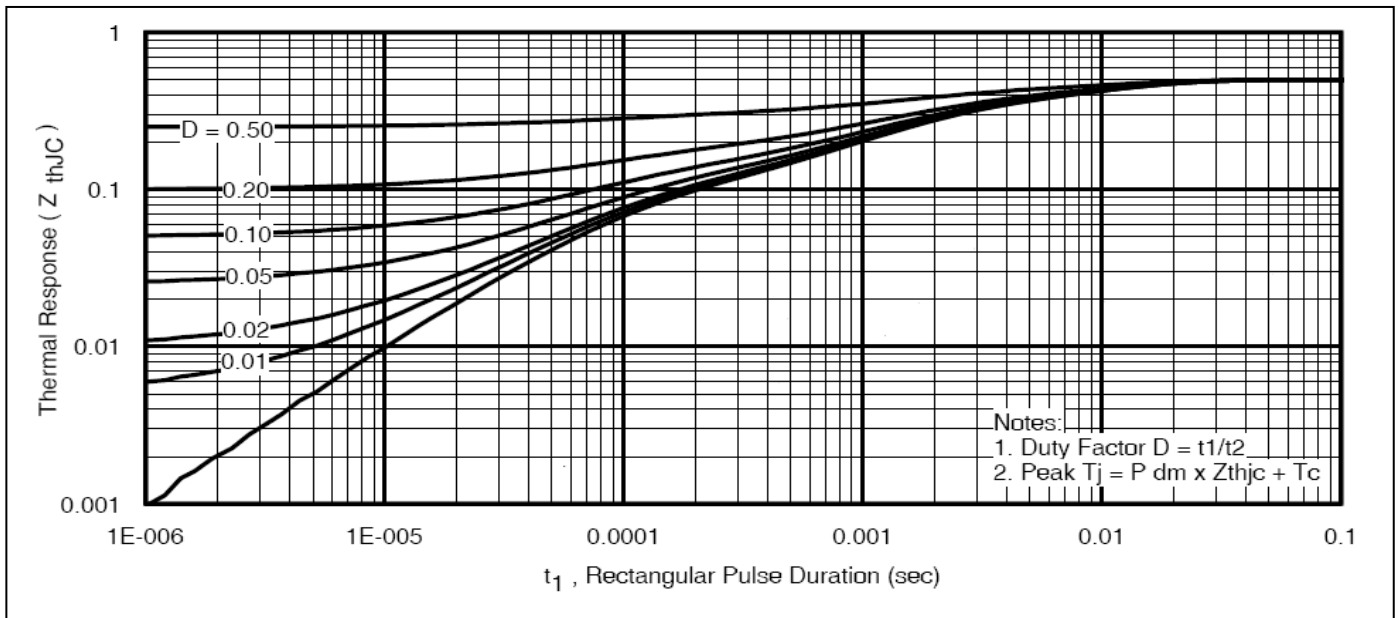
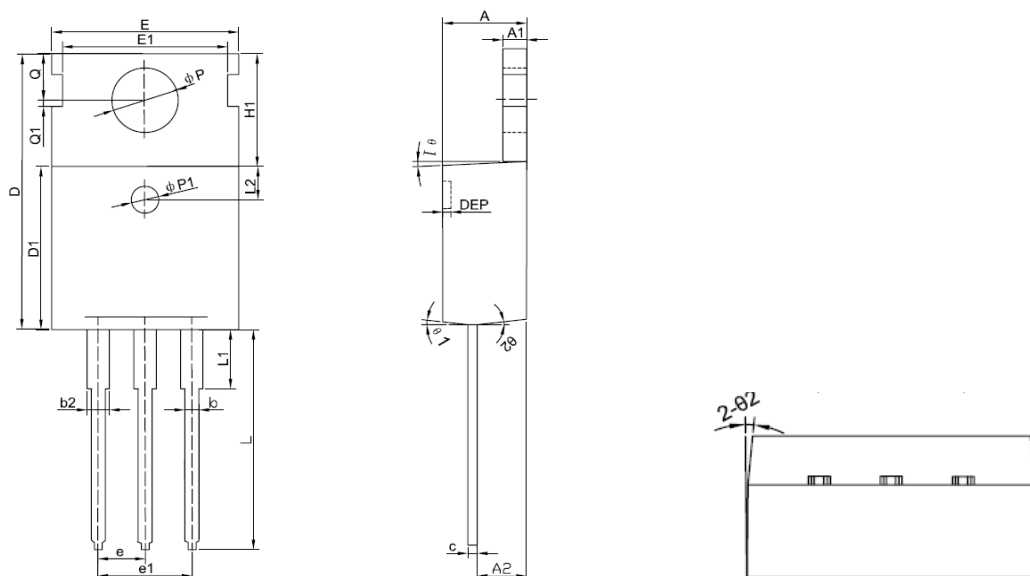


Figure 7. Maximum Effective Transient Thermal Impedance, Junction-to-Case

Mechanical Data:
TO220 PACKAGE OUTLINE DIMENSION


Symbol	Dimension In Millimeters			Dimension In Inches		
	Min	Nom	Max	Min	Nom	Max
A	4.400	4.550	4.700	0.173	0.179	0.185
A1	1.270	1.300	1.330	0.050	0.051	0.052
A2	2.590	2.690	2.790	0.102	0.106	0.110
b	0.770	-	0.900	0.030	-	0.035
b2	1.230	-	1.360	0.048	-	0.054
c	0.480	0.500	0.520	0.019	0.020	0.020
D	15.100	15.400	15.700	-	0.606	-
D1	9.000	9.100	9.200	0.354	0.358	0.362
DEP	0.050	0.285	0.520	0.002	0.011	0.020
E	10.060	10.160	10.260	0.396	0.400	0.404
E1	-	8.700	-	-	0.343	-
ΦP1	1.400	1.500	1.600	0.055	0.059	0.063
e	2.54BSC			0.1BSC		
e1	5.08BSC			0.2BSC		
H1	6.100	6.300	6.500	0.240	0.248	0.256
L	12.750	12.960	13.170	0.502	0.510	0.519
L1	-	-	3.950	-	-	0.156
L2	1.85REF			0.073REF		
ΦP	3.570	3.600	3.630	0.141	0.142	0.143
Q	2.730	2.800	2.870	0.107	0.110	0.113
Q1	-	0.200	-	-	0.008	-
Θ1	5 ⁰	7 ⁰	9 ⁰	5 ⁰	7 ⁰	9 ⁰
Θ2	1 ⁰	3 ⁰	5 ⁰	1 ⁰	3 ⁰	5 ⁰

Ordering and Marking Information
Device Marking: SSF7505

Package (Available)
TO220
Operating Temperature Range
C : -55 to 175 °C

Devices per Unit

Package Type	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO220	50	20	1000	6	6000

Reliability Test Program

Test Item	Conditions	Duration	Sample Size
High Temperature Reverse Bias(HTRB)	$T_j=125^{\circ}\text{C}$ to 175°C @ 80% of Max $V_{DSS}/V_{CES}/V_R$	168 hours 500 hours 1000 hours	3 lots x 77 devices
High Temperature Gate Bias(HTGB)	$T_j=150^{\circ}\text{C}$ or 175°C @ 100% of Max V_{GSS}	168 hours 500 hours 1000 hours	3 lots x 77 devices

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